

Application No.: 10/802,549

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Docket No.: 524322000600

REMARKS

In a non-final Office Action mailed on January 31, 2006, claims 12-15 and 21-25 have been allowed. The Office Action Summary of the Office Action indicated that claims 1 and 8 were rejected and claims 2-7 and 9-11 were objected to. In the Detailed Action, however, it appears that the Examiner intended to reject claim 5. The following assumes that claim 5 was rejected. Applicant respectfully requests reconsideration of these pending claims.

I. Rejection of Claims 1, 5, and 8 under 35 U.S.C. § 102(e)

The Examiner rejected claims 1, 5, and 8 under 35 U.S.C. § 102(e) as being anticipated by Subramanian (U.S. 6,756,796) ("the Subramanian reference").

The Applicant respectfully disagrees. Claim 1 recites "obtaining a die placement of dice to be formed on the wafer" (emphasis added). Therefore, the "die placement" recited in claim 1 is of dice that will be formed on the wafer in a future fabrication process.

In rejecting claim 1, the Examiner cites to Figs 1 and 2 of the Subramanian reference as disclosing the recited die placement. The Subramanian reference, however, clearly discloses that Figs. 1 and 2 depict dies that have already been formed on the wafer. In particular, column 1, lines 49-56 disclose:

"In the manufacture of semiconductor devices, wafers are formed with an incomplete circular edge terminating in a flat edge. The wafers are patterned into multiple dies separated by streets or saw cut lines to separate the dies. Some of these dies are good dies, some are full pattern dies and some are not, some are mirror dies, there may be plug dies or an ink die. FIG. 1 illustrates these dies and the wafer edge."

Column 2, lines 4-9 disclose:

"After the wafer is placed on the pick and place equipment, this equipment looks for the reference die. In the existing equipment in one wafer system, the reference die is found as illustrated in FIG. 2 by moving the wafer table down from the center of the wafer toward the flat until the monitor shows the mirror die along wafer flat row."

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Because the Subramanian reference fails to disclose or suggest, "obtaining a die placement of dice to be formed on the wafer" or "adjusting the die placement" as recited in independent claim 1, Applicant asserts that claim 1 is allowable. Applicant also asserts that claims 5 and 8, which depend from claim 1, are allowable for at least the reason that they depend from an allowable independent claim.

II. Allowable Subject Matter

The Applicant thanks the Examiner for indicating claims 12-15 and 21-25 are allowable.

The Examiner indicated claims 2-4, 6-7, and 9-11 are objected to as being dependent upon the rejected base claim 1, but allowable. Applicant asserts that claims 2-4, 6-7, and 9-11, which depend from claim 1, are allowable for at least the reason that they depend from an allowable independent claim.

The Examiner indicated claims 3-4 and 7 are allowable if rewritten in independent form because they are dependent on objected claims 2 and 6. Applicant asserts that claim 3-4 and 7, which depend from claim 1, are allowable for at least the reason that they depend from an allowable independent claim.

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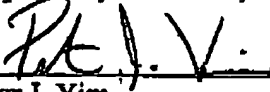
III. Conclusion

In view of the above, each of the presently pending claims in this application is believed to be in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to withdraw the outstanding rejection of the claims and to pass this application to issue. If it is determined that a telephone conference would expedite the prosecution of this application, the Examiner is invited to telephone the undersigned at the number given below.

In the event that the U.S. Patent and Trademark office determines that an extension and/or other relief is required, Applicant petitions for any required relief including extensions of time and authorizes the Commissioner to charge the cost of such petitions and/or other fees due in connection with the filing of this document to Deposit Account No. 03-1952 referencing docket no. 524322000600. However, the Commissioner is not authorized to charge the cost of the issue fee to the Deposit Account.

Dated: April 7, 2006

Respectfully submitted,

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